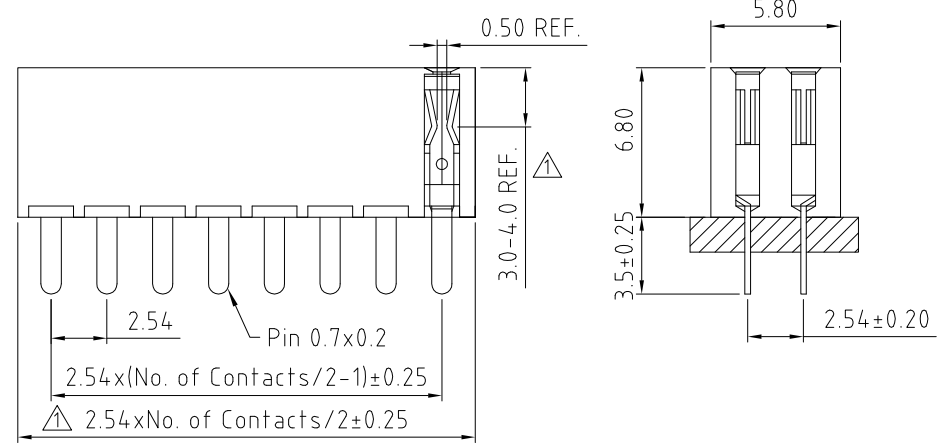
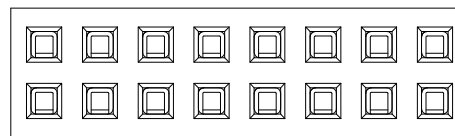


BB02-KG:- 2.54mm X 2.54mm (0.1" X 0.1") SOCKET, DUAL ROW, STRAIGHT, THROUGH HOLE - 4 TO 60 CONTACTS, CLOSED BOTTOM TYPE

SPECIFICATIONS

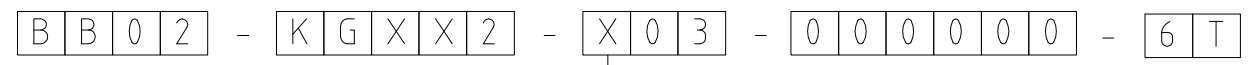
CURRENT RATING 3 AMPS
 INSULATOR RESISTANCE 1000 MEGOHMS MIN.
 CONTACT RESISTANCE 20 M OHMS MAX
 DIELECTRIC WITHSTANDING AC 600 V
 OPERATING TEMPERATURE -40°C TO +105°C
 CONTACT MATERIAL PHOSPHOR BRONZE
 INSULATOR MATERIAL POLYESTER UL 94V-0
 NYLON 6T : STANDARD
 PBT : SPECIAL OPTION
 PLATING GOLD, TIN OR SELECTIVE OVER 30-50U" NICKEL
 SOLDERABILITY: NYLON 6T - IR REFLOW: 260°C FOR 10 SEC
 WAVE: 230°C FOR 5-10 SEC
 MANUAL SOLDER: 350°C FOR 3-5 SEC
 PBT - MANUAL SOLDER: 330°C FOR 3-5 SEC
 (NOT SUITABLE FOR HI-TEMP PROCESS)



NOTES:
 1. PACKED IN TUBES.
 2. RECOMMENDED MATING PIN LENGTH: 5.0MM. Δ

MATES WITH: - BB02-HE BB02-TD
 BB02-HJ BB02-TF
 BB02-HP BB02-TG
 BB02-HU BB02-TH

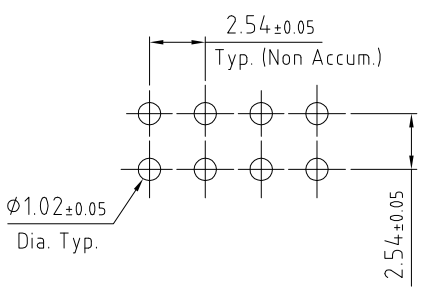
HOW TO ORDER



NO. OF CONTACTS:
 04 TO 60 Δ

CONTACT PLATING OPTIONS:
 K = GOLD FLASH (STANDARD)
 T = BRIGHT TIN
 M = MATT TIN
 D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL

INSULATOR MATERIAL: Δ
 6T = NYLON 6T (STANDARD)
 BLANK = PBT (Not suitable for new designs.)



RECOMMENDED PC BOARD HOLE LAYOUT

REV. DATE & DRN.	1.1 12/08/02 - AMCI RELEASE
Δ DRAWING MODIFICATION, AMEND DIMENSIONS.	1.1 09/06/06 - NYW
Δ DRAWING MODIFICATION, ADD PLASTIC OPTIONS, ADD NOTES 2.	1.2 29/05/07 - NYW
Δ AMEND NO. OF CONTACTS.	1.3 28/04/08 - CHC
Δ ADD MATT TIN PLATING.	1.4 30/05/08 - PN
Δ DRAWING MODIFICATION.	1.5 13/07/09 - NYW
Δ REMOVE THICK GOLD PLATING OPTIONS.	1.6 29/12/09 - NYW
Δ AMEND MATING PIN LENGTH.	1.7 12/03/14 - NYW

Scale:	4:1
Drawn:	A.MCI
App'd:	XXXX
Date:	12 MAR '14

THIRD ANGLE	
Title	SOCKET
Revision:	1.7

Unstated Tolerances:	X ± 0.30 X ± 0.25 .XX ± 0.15 .XXX ± 0.10
----------------------	---

Material	SEE NOTE
NOT TO SCALE	
Unit:	mm

www.gradconn.com

THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT

Type:	BB02-KG
Drawing Number:	BB02-KG
Sheet	1 of 1
Drawing	© E and O E